

ABSTRACT OF THE DISCLOSURE

MULTILAYER PRINTED WIRING BOARD

A multilayer printed wiring board comprising a plurality of interlaminar insulating layers, a plurality of insulating circuit boards having circuits formed on the insulating substrates, and via holes for making electrical connection between two or more layers of circuits, wherein the difference between the glass transition point of an interlaminar insulating layer and that of the adjoining insulating substrate is not greater than 60°C, is proof against exfoliation due to heat history of the board and has high reliability of insulation and through-hole connection.

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REPLACED

This Sheet Has Been Replaced

